



PRELIMINARY SPECIFICATION

Part No.: TDRF2545B290

Customer:

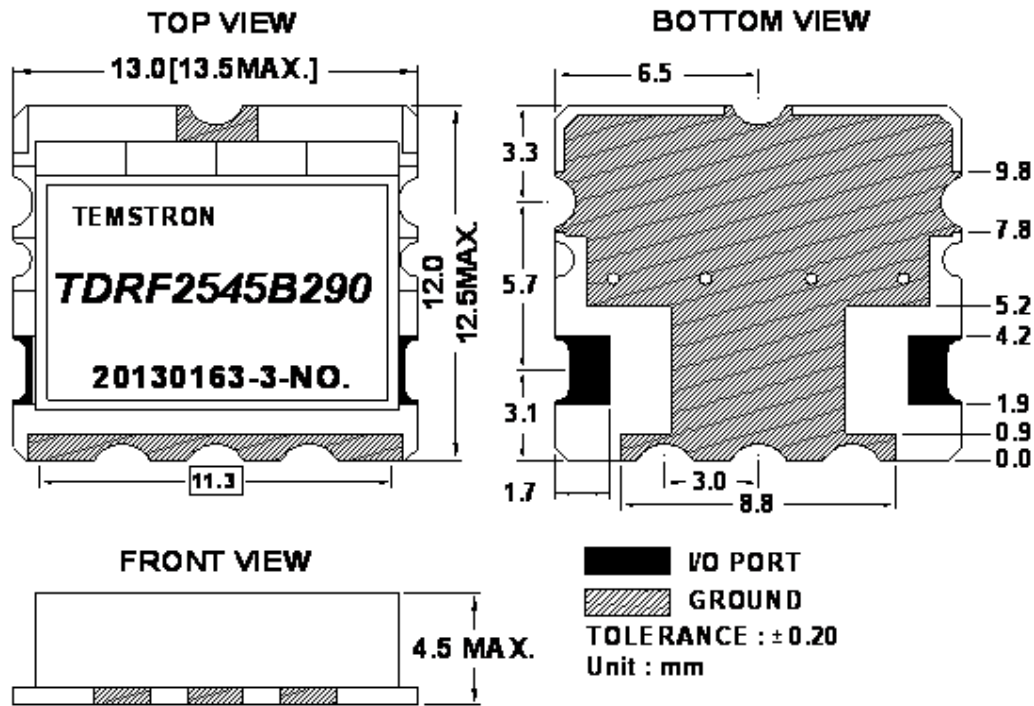
Date: 2013-11-14

Written by	Checked by	Approval
P. H. Hong	M. Y. Chen	C. K. Chang

ELECTRICAL SPECIFICATIONS

ITEM	SPEC	UNIT	
1	Center Frequency [fo]	2545	MHz
2	Bandwidth [BW]	$fo \pm 145.00$ [2400.00~2690.00]	MHz
2	Insertion Loss at BW	3.00	dB max.
4	Ripple in BW	1.00	dB max.
5	V.S.W.R in BW	2.00	max.
6	Attenuation [Absolute Value]	10.0 dB min.@ fo = 2300.00 7.0 dB min.@ fo = 2790.00	MHz
7	In/Out Impedance	50	Ω
8	Operation Temperature Range	-40~+85	
9	Return Loss in BW		dB min.
10	Group Delay Variation		ns max
11	Input Power	2.0	W max.

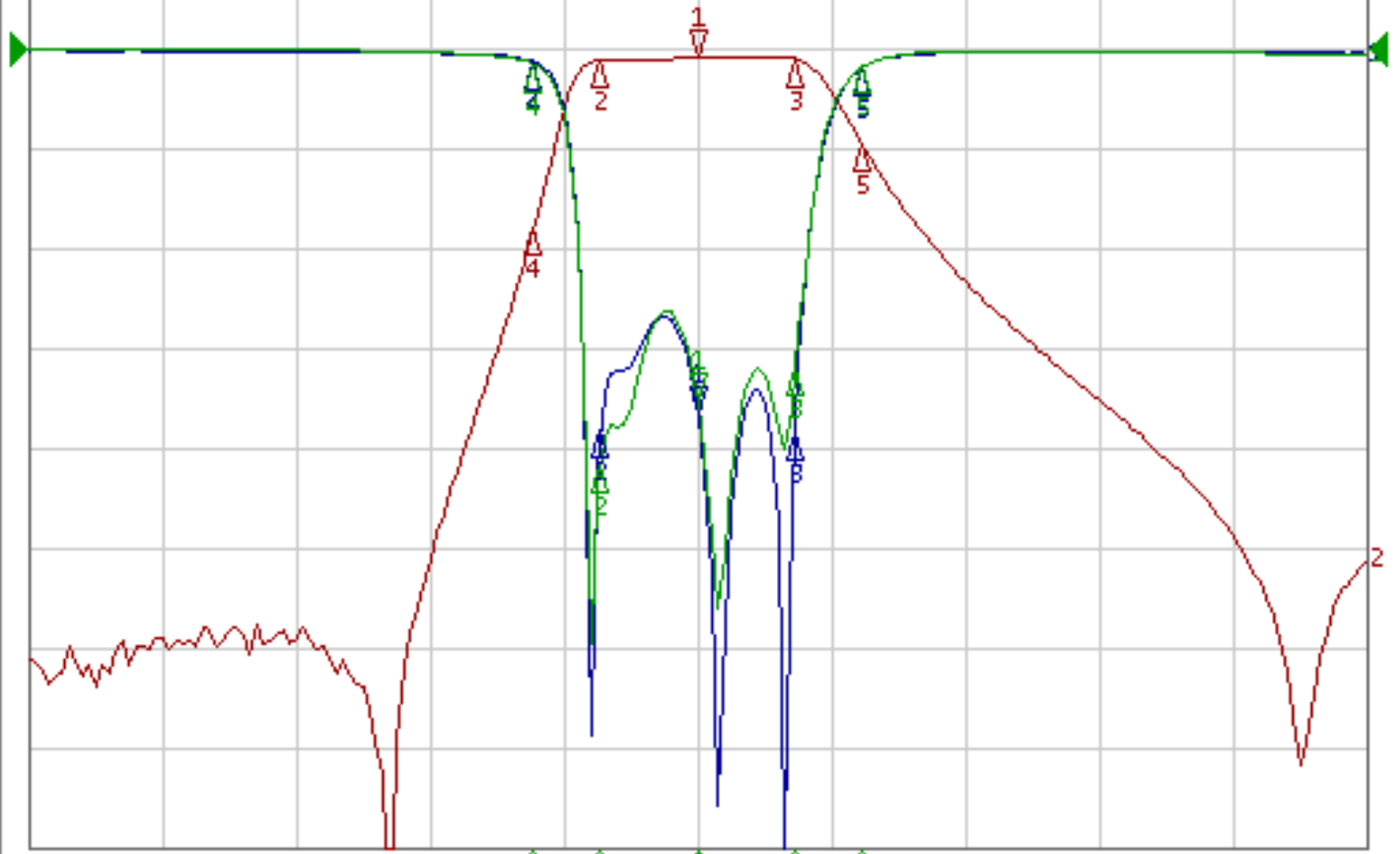
MECHANICAL SPECIFICATION



PLOT DATA

Tr1 S11 Log Mag 5.000dB/ Ref 0.000dB [F3]
Tr2 S21 Log Mag 10.00dB/ Ref 0.000dB [F3]
▶ Tr3 S22 Log Mag 5.000dB/ Ref 0.000dB [F3]

1	2.5450000 GHz	-0.7048 dB	>1	2.5450000 GHz	-17.557 dB
2	2.4000000 GHz	-1.0371 dB	2	2.4000000 GHz	-20.760 dB
3	2.6900000 GHz	-0.9216 dB	3	2.6900000 GHz	-15.987 dB
4	2.3000000 GHz	-17.764 dB	4	2.3000000 GHz	-0.7186 dB
5	2.7900000 GHz	-9.3452 dB	5	2.7900000 GHz	-0.8320 dB

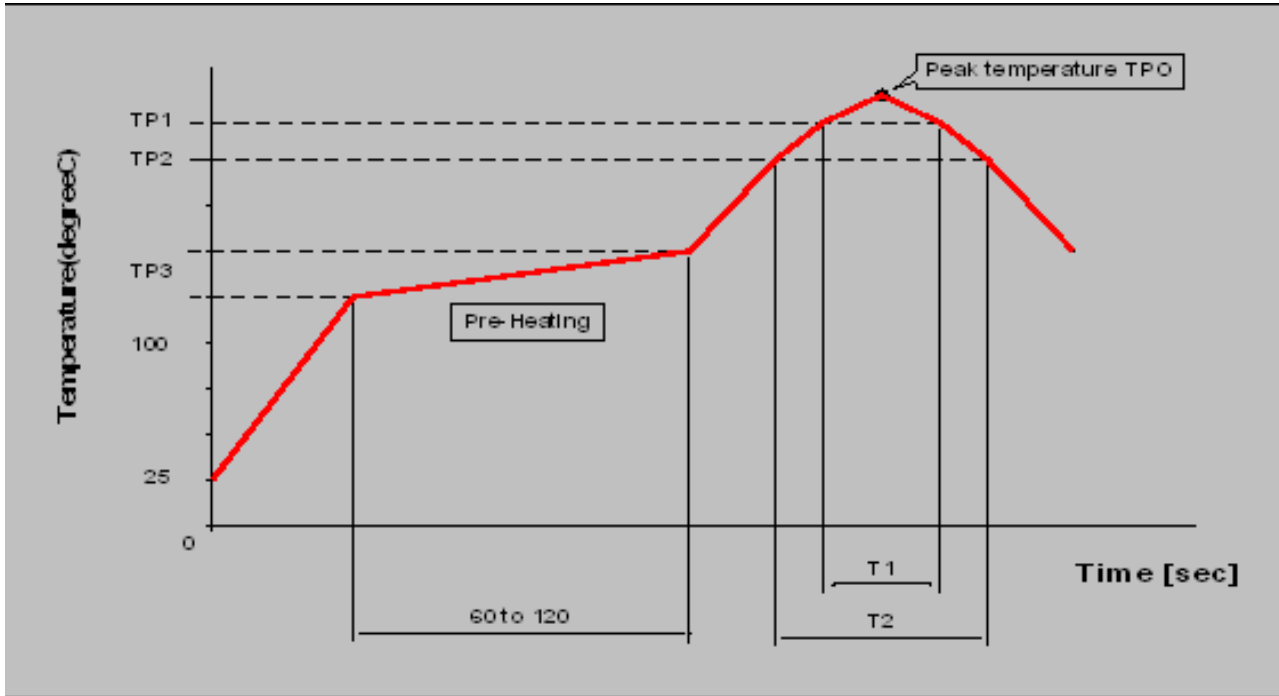


1 Center 2.545 GHz

IFBW 70 kHz

Span 2 GHz C? |

SOLDERING CONDITION



Measuring point of temperature : IN OUT Terminals of The Device

Reflow Soldering : Both Convection and Infrared Rays, Hot Air and Hot Plate

Reflow standard condition	TP0 ()	TP1 ()	T1 (s)	TP2 ()	T2 (s)	TP3 ()
Sn-3Ag-0.5 solder	245+/-5	220	30 to 60	—	—	150 to 180
Test condition of reflow heat resistance	260+5/-0	240	20	220	70	150 to 180